TAPE Attachment Method

Part Number: 374424B00035G





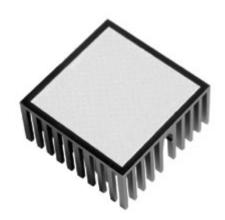
This part is in stock and available for immediate delivery

Contact your local sales rep

BGA Surface	Таре Туре	Heat Sink Finish
Plastic	<u>T411</u>	Black Anodize

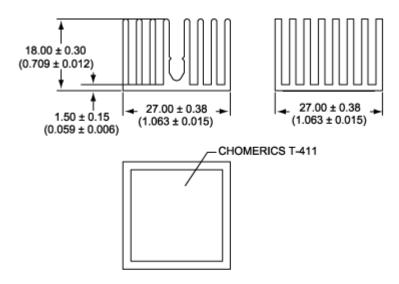
Features and Benefits

- Configurations are available for a wide range of BGA package sizes
- Tape mounted versions eliminate the need for mounting holes in the PC Board
- These Heat Sinks can be used with either plastic or metal/ceramic BGA Packages depending on tape used
- These Heat Sinks are compatible with Ther-a-grip tapes



Width	Length	Height	Fin Thickness Across Width	Fin Thickness Across Length	Base Thickness	# of fins across width	# of fins across length
27mm	27mm	18mm	1.40mm	1.63mm	1.50mm	8	8

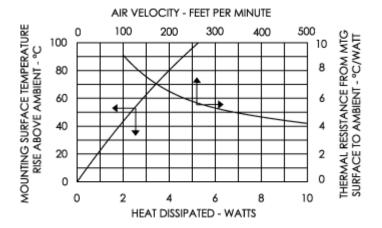
Mechanical Outline Drawing



Unless otherwise shown, tolerances are $\pm 0.38(\pm .015)$

Thermal Performance

*θn	**0f	
20.3	6.46	



^{*}Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.

This data sheet represents only one of a broad range of products we make to cool electronics. Our representatives can help you configure a complete cooling solution for your individual applications.

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^{**}Forced convection thermal resistance based on an entering 1.0 m/s (200 lfm) airflow. Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.